Application No. 10/020,506

- 57. The printed wiring board of claim 56, wherein the carbon containing layer comprises a substrate containing carbon impregnated with a resin.
- 58. The printed wiring board of claim 57, wherein the substrate comprises we'ven carbon fibers.
- 59. The printed wiring board of claim 57, wherein the carbon containing layer comprises unidirectional carbon fibers.
- 60. The printed wiring board of claim 57, wherein the resin is an electrically conductive resin.
- 61. The printed wiring board of claim 60, wherein the electrically conductive resin has a dielectric constant greater than 6.0 at 1 MHz.
 - 62. The printed wiring board of claim 60, wherein the electrically conductive resin contains a pyrolytic carbon additive.
 - 63) The printed wiring board of claim 60, wherein the electrically conductive resin contains a silver oxide additive.
 - 64. The printed wiring board of claim 60, wherein the electrically conductive resin contains carbon powder as an additive.

Application No. 10/020,506

5. The printed wiring board of claim 57, wherein:

the carbon containing layer is clad on one side with the electrically conductive layer; and

the electrical connection between the carbon containing layer and the electrically conductive layer is established by contact between the carbon in the carbon containing layer and the electrically conductive layer.

- 66. The printed wiring board of claim 56, wherein the carbon containing layer comprises a carbon plate.
- 67. The printed wiring board of claim 56, wherein the carbon containing layer and the electrically conductive layer are separated by a prepreg.

91

- 68. The printed wiring board of claim 67, wherein:
 the prepreg contains electrically conductive resin; and
 the electrical connection between the carbon containing layer and
 the electrically conductive layer is created through the electrically
 conductive resin.
- 69. The printed wiring board of claim 68, wherein the electrical connection between the carbon containing layer and the electrically conductive layer is created by through plated vias extending through the electrically conductive layer and the carbon containing layer.

REMARKS

For the record, the applicant wishes to record that the Examiner contacted the applicant and requested that a restriction requirement be made in relation to four groups of claims. Applicant wishes to characterize new claims 56 - 69 as an election and wishes to preserve the right to pursue the unelected claims in future continuation